Product End-of-Life Disassembly Instructions

Product Category: Calculators
Marketing Name / Model [List multiple models if applicable.]
HP MSR30-20,RTUZ73020,Router Host,TAA,（JG729A）
HP MSR30-20,RTUZ83020,Router Host(DC),TAA,（JG728A）
HP A-MSR30-20,RTVZA3020,Router Host,（JF284A）
HP A-MSR30-20,RTVZB3020,Router Host (DC),（JF235A）

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing		0

PSG instructions for this template are available at EL-MF877-01

radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew all screws 1, and then remove the mounting angle 2.
2. Unscrew all screws 3, and then remove part 4.
3. Unscrew all screws 5, and then remove PCB 6.
4. Unscrew all screws 5, and then remove PCB 7.
5. Remove panel 8 from the PCB 9
6. Unscrew the screws on PCB 9, and then remove PCB 9.
7. Unscrew the screws on PCB 10, and then remove PCB 10
8. Unscrew the screws on PCB 11, and then remove PCB 11.
9. Unscrew the screws on PCB 12, and then remove PCB 12.
10. Unscrew the screws on PCB 13, and then remove PCB 13.
11. Unscrew the screws on part 14, and then remove part 14.
12. Unscrew the screws on part 15, and then remove prt 15.
13. Unscrew all screws 16, and then remove part 17.
14. Unscrew all screws 18, and then remove fan 19.
15. Remove panel 20 from the part 23.
16. Unscrew all part 21, and then remove part 22.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

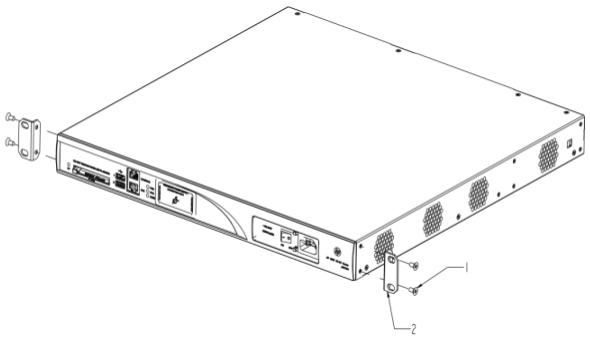

Figure 1 Treatments to the product

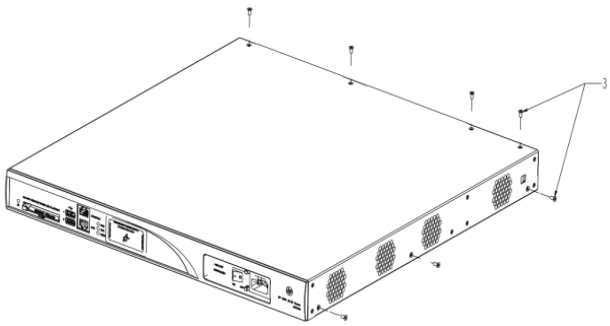

Figure 2 Treatments to the product

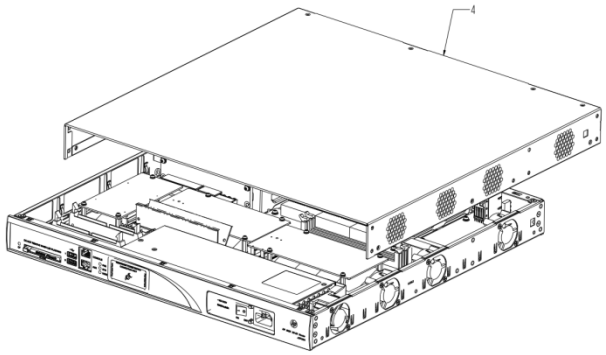

Figure 3 Treatments to the product

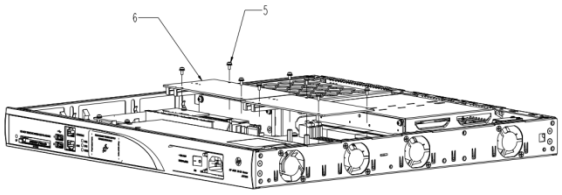

Figure 4 Treatments to the product

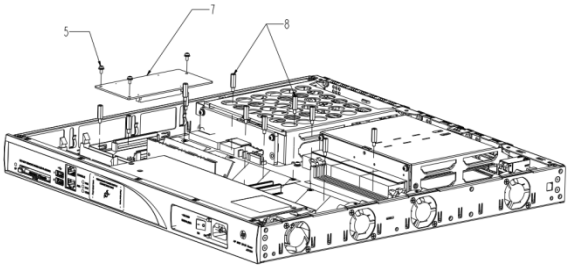

Figure 5 Treatments to the product

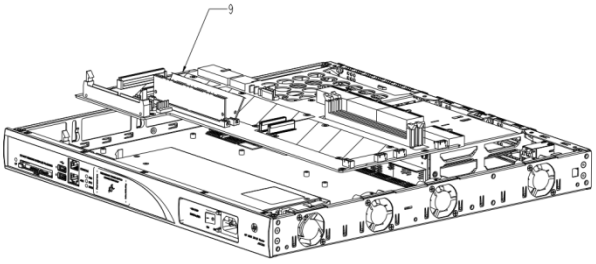

Figure 6 Treatments to the product

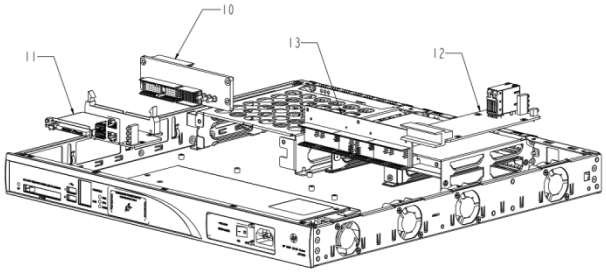

Figure 7 Treatments to the product

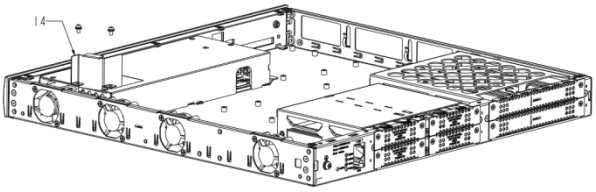

Figure 8 Treatments to the product

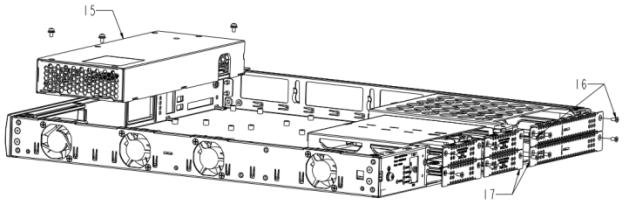

Figure 9 Treatments to the product

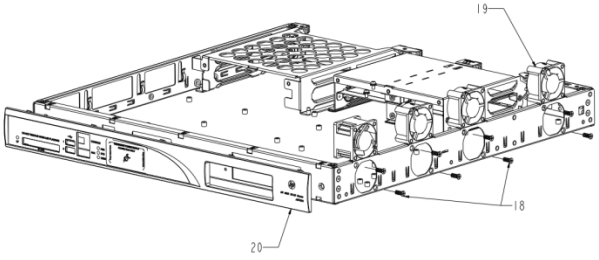

Figure 10 Treatments to the product

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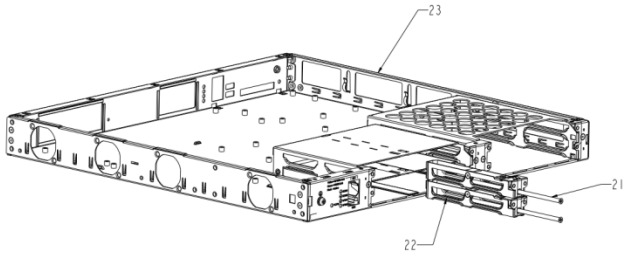

Figure 11 Treatments to the product

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	2	Fe	37.2	0.6%		Fe recycling
	4	Fe	1930	29.7%		Fe recycling
	6	Complex PWB	130.8	2.2%	The surface of PCB is greater than 10 square centimeters;	
	7	Complex PWB	48.2	0.7%	The surface of PCB is greater than 10 square centimeters;	
	9	Complex PWB	378.5	5.9%	The surface of PCB is greater than 10 square centimeters;	
	10	Complex PWB	86.9	1.3%	The surface of PCB is greater than 10 square centimeters;	
	11	Complex PWB	123.5	1.9%	The surface of PCB is greater than 10 square centimeters;	
	12	Complex PWB	65.3	1.1%	The surface of PCB is greater than 10 square centimeters;	
	13	Complex PWB	79.6	1.3%	The surface of PCB is greater than 10 square centimeters;	
	14	Fe	16.8	0.2%		Fe recycling
	15	PBT , Cu	486	7.4%	Containing brominated flame retardants	Pla recycling Cu recycling
	17	Fe	124.4	1.9%		Fe recycling
	19	PBT , Cu	165.6	2.5%	Containing brominated flame retardants	Pla recycling Cu recycling
	20	PBT	40.5	0.8%	Containing brominated flame retardants	Pla recycling
	21	Fe	28.8	0.4%		Fe recycling
	22	Fe	105.4	1.6%		Fe recycling
	23	Fe	2655.4	40.5%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2013.08.13	V0	Liu Jia	Initial version
2013.09.17	V1	Liu Jia	Add the module JF284A AND JF235A